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DOCUMENT

ESA Generic Product Tree

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1 INTRODUCTION

1.1 Objective of this Document

The objective of this document is to present the ESA Generic Product Tree (GPT), which provides a generic, structured and complete classification of space products.

The ESA Generic Product Tree presented herein may be subject to evolution and modification in time.

1.2 Historical Background

There already exist many Product Trees which aim to classify products. However, they vary from project to project depending on the mission type and contractor.

A need to have a generic structure to classify space products when carrying out a complete mapping of the industry capabilities has been identified by D/TEC.

To this end, a Generic Product Tree has been prepared by TEC-SGH in close coordination with technical experts from ESA Directorates.

The document was first distributed within ESA and externally to National Delegations and European Industry, as Technical Note in November 2010. In July 2011 has been updated for publication as ESA STM being the present issue (issue 1.1) the result of this update.

1.3 Objective and Structure of the ESA Generic Product Tree

The objective of the ESA Generic Product Tree is to provide a generic, structured and complete classification of all the products involved in space activities.

It will find particular use in databases collecting products and/or company information.

The Generic Product Tree is broken down into several levels. The number of levels depends on the product and therefore varies across the tree.

The first level of decomposition introduces 4 Segment Levels (SL):

- (I) Launchers
- (II) Satellites & Probes
- (III) Orbital Transportation & Re-entry Systems
- (IV) Ground Segment

Each <u>Segment Level</u> (SL) is further subdivided into <u>Systems</u>, which are then classified according to their integration level. For instance, Segment II "Satellites & Probes" has been classified as follows:

	Segment		Systems
II	II Satellites & Probes		AOCS & GNC
		В	Electronics
		U	Materials
		D	Mechanisms
		Е	On-board SW
		F	On-board Data Management



Segment		Systems
	G	Optical Communication
	Н	Parts
	I	Payloads/Instruments
	J	Power
	K	Propulsion
	L	RF / Microwave Communication (Platform and Payloads)
	М	System Engineering Software
	N	Structures
	0	Thermal Control
	Р	Other

1.3.1 Nomenclature

In order to overcome the ambiguity related to the use of generic terms such as "equipment", "subsystem", etc., a definition of the nomenclature as it has been used within the Generic Product Tree is hereinafter reported:

Product: Generic term, which may refer to: Equipment, Building Blocks or Components & Parts. All products have been classified as one of the following:

- Equipment
- Building Blocks (BB)
- EEE Components, mechanical Parts and materials (C&P)

Where:

Equipment: Unit at high integration level performing a high-level function or set of functions. In this perspective, a "Star tracker" can be considered as equipment but a charge-coupled device (CCD) detector cannot.

Building Blocks (BB): Unit at low integration level which must be utilised as part of a higher integration level to perform a high level function, allowing re-use without major non-recurrent system adaptations. For example, a CCD detector can be considered a BB.

EEE Components, mechanical Parts and materials (C&P): Unit at the lowest integration level.

1.3.2 Colour code

A colour code is applied in order to offer a friendly and intuitive tree representation at Product decomposition level:

Products:

Equipment

Building Blocks (BB)

EEE Components, mechanical Parts and materials (C&P)

Depending on the product addressed, the classification granularity applied differs, as it is closely related to the supply chain of the specific Segment:

- Launchers: Equipment, BB and C&P
- Satellites & Probes: Equipment, BB and C&P

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- Orbital Transportation & Re-entry Systems: Equipment and BB
- Ground Segment: Equipment

1.4 Product Classification Criteria

Products may be classified according to a variety of criteria, i.e. academic/functional classification, technology oriented, or mirroring, for instance, the specific internal organisational structure of a company.

The classification adopted for the ESA Generic Product Tree structures the products through a "<u>Product Utilisation/Design point of view</u>". According to this perspective, the sub-criteria applied are the following:

 Stand-alone/end-products with different integration levels (Equipment, BB, etc.) are classified according the System level they belong to.

Examples:

- Power Conditioning Equipment and Battery Charge Regulators BB → Power System
- Thrusters Equipment and Fill & Vent valves C&P → Propulsion System
- BB and C&P common to more than one System are grouped together.

Examples:

- Mechanisms
- EEE components
- For BB and C&P common to two or more Systems but not numerous enough to be grouped into a distinctive System, a "case by case" approach has been adopted:

The equipment is assigned to one system and a reference to the assigned system is then specified in the other system(s) under which it appears. This is the case of BB and C&P performing functions related to different systems, for which it is difficult to assign a "clearly identifiable and unique home".

Examples:

- Tanks BB: They appear under II-K-1.1-c, with a reference to "Structures" (II-N), where they are separated in two BB: "Pressure Tanks" (II-N-all.1-c) and "Propellant Tanks" (II-N-all.1-d).
- CCD Detectors BB: It appears under II-A-1.1 "Sensors" and under II-G-1.1 for Optical Cameras, with the note *See AOCS&GNC.

It is worth noting that since the GPT will be mainly implemented in databases, the reference pointing to another field is transparent to the final users.

• For each Equipment/BB/C&P, a further classification is proposed in the "Description" column. The criteria and granularity of this further level of classification differs according to the related branches: in some cases, the classification is intuitive (e.g. AOCS), while in other cases it may be more complex, as multiple choices are possible (e.g. RF/Microwave Communication). In any case, a higher level of granularity of this further classification level is out of scope of the Generic Product Tree.

Examples:

- AOCS (II-A) → Sensors: Gyros / Accelerometers / Earth sensors / ...
- RF/Microwave Communication (II-L) → "Transmitters" can be classified by: Payload or Platform transmitters / Application (Near Earth application, Deep space application, Orbiter-Rover link, etc.) / Frequency band (X-band, S-band, etc.).
- The GPT focuses on branches and leaves corresponding to re-usable/customisable products; therefore, only in few cases mission-specific equipment is included.

Example:

 On-board Software elements often consist in mission-specific software embedded applications, which are extensively produced in-house.



2 ESA GENERIC PRODUCT TREE

2.1 Launchers

Launci	egment		Systems		Products: Equipment/Building Blocks/EEE Components, mechanical Parts and materials		Description
	nchers	Α	Avionics	1	On-Board Computers	а	*See Software
				2	Data systems and I/F	а	Communication buses, harness, connectors,
				3	Power Storage, Conditioning and and Distribution -	а	Batteries
					Equipment	b	Power conditioning and distribution units
				3.1	Power Storage, Conditioning	а	Current and voltage sensors and limiters
					and and Distribution - BB	b	Heater Control
				1	GNC Units	С	Other IMU, IMU/GPS *See Software
				5	TT&C	a a	Antennas, transmitters, receivers, transponders
				6	Safeguard Electrical Systems	_	Safe and arme devices,
				7	TVC control electronics	a	
				8	Others	a	*See Software
		В	Descent &	1	Descent	a	Sequential units, Parachutes
		ľ	Recovery	2	Recovery		
		С	Electronics			а	Beacon
		ľ	Liectionics	1	EEE Components	a b	Capacitors Connectors
			1			С	Crystals
						d	Discrete semiconductors (including diodes, transistors)
						е	Filters
						f	Fuses
						g	Magnetic components (e.g. Inductors, Transformers)
						h	Monolithic Microcircuits (including MMICs)
						i	Hybrid circuits
						j	Relays
						k	Resistors, heaters
						- 1	Surface acoustic wave devices
						m	Switches (including mechanical, thermal)
						n o	Thermistors Wires and cables
						р	Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors)
						q	Passive Microwave Devices (including e.g. mixers, couplers, isolators and switches)
						r	Other
		D	Materials	1	Metallic		
				2	Non-metallic		
				3	Composite Materials	а	Reinforcement Material: Glass Fibres
						b	Reinforcement Material: Carbon Fibres
						С	Reinforcement Material: Aramid Fibres Reinforcement Material: Silicon Carbide, both Fibre and
						d	Particulate (SiC)
						е	Reinforcement Material: Alumina, both Fibre and Particulate (Al_2O_3)
						f	Reinforcement Material: New polymeric fibres
			1			g	Reinforcement Material: Others
						h	Matrix Structure: Epoxy
						i	Matrix Structure: Cyanate Ester
			1			j	Matrix Structure: Ceramic (SiC)
						k I	Matrix Structure: Metal (AI, Ti, C) Matrix Structure: Others
		E	Mechanisms	1	Mechanisms - Units	а	Hold down and release
		ľ			Tallanding Sincs		Pyrotechnics
						С	Safety and Destruction Systems
						d	Stage/Payload Separation devices - not explosive
							(Clamp-bands, springs,)
						e f	TVC Actuators Others



	Segment		Systems		Products: Equipment/Building Blocks/EEE Components, mechanical Parts and		Description
_	-	_	_		materials		
I	Launchers	F	Parts	1	Mechanical and Magnetic Parts	а	Connecting Parts (nuts, bolts,), Separating Parts (springs, cutters,), Spacing Parts, Bearing Parts, Control Parts (gears), etc.
						b	Magnetic Parts
						С	Other
		G	Propulsion	1	Liquid propulsion systems		
				1.1	Liquid propulsion systems -	а	Propellant Tanks *See Structures
					BB	b	Pressure Tanks *See Structures
						С	Feeding system devices (feed lines, filters, valves,)
				2	Storable liquid engines		
				3	Cryogenic liquid engines		
				4	Hydrocarbon liquid engines		
				2/3/4.1	Liquid propulsion engines -	а	Combustion chambers
					ВВ	b	Flow control and distribution devices (Pipes, Valves, Actuators, Filters,)
						С	Gas generators (gas generetor cycle engine)
						d	Nozzles
						е	Pre-burners (stage combustion cycle engine)
						f	Turbo-pumps
	ĺ					g	Other
				5	Solid propulsion motors		
				5.1	Solid propulsion motors - BB	а	Motor Cases (metallic, composite)
						b	Thermal Protection
						С	Propellant Grain
						d	Igniters
						e f	Nozzles Other
				6	Reaction and Attitude Control	Ė	Other
				_	Systems		
				6.1	Reaction and Attitude Control	а	Thrusters
					Systems - BB	b	Flow control and distribution devices
						С	Tanks *See Structures
				7	Duran Islam Contain CW	d	Other
		н	Software	1	Propulsion System SW Flight SW	а	SW tools for propulsion system and engine design, analysis, simulation, etc.
		l''	Software	1	I light 3W	a b	On-Board computers Inertial Measurement Units (IMUs)
						С	Thrust-Vector Control (TVC)
						d	Other
				2	System Engineering SW (for operational Ground SW see	а	Dependability, Safety and Quality Tools (RAMS, FMECA,)
					Segment III)	b	Mission Analysis tools (Trajectory computation; Propellant masses optimisation; Stage fall-down, Orbital modelling and simulation,)
						С	System Modelling & Simulation (Aerothermodynamic Tools for Design, Environment,)
		1	1				
			<u> </u>			d	Other
		I	Structures	1	Stage structures	d a	Other Intestages, skirts, thrust frame,
		I	Structures	1 2	Tanks		
		I	Structures	3	Tanks Propellant tanks		
		I	Structures	3	Tanks Propellant tanks Pressure tanks		
		ī	Structures	3 4 5	Tanks Propellant tanks Pressure tanks Fairing		
		1	Structures	3	Tanks Propellant tanks Pressure tanks Fairing Payload adapters		
		1	Structures	3 4 5	Tanks Propellant tanks Pressure tanks Fairing	a	Intestages, skirts, thrust frame,
		ī	Structures	3 4 5 6 7	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other		Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings,
		ī	Structures	3 4 5 6 7 1/2/3/4/	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other	a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls
		ī	Structures	3 4 5 6 7 1/2/3/4/ 5/6/7.1	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB	a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other
				3 4 5 6 7 1/2/3/4/ 5/6/7.1	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB	a a b	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls
		ī	Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection	a a b	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc.
				3 4 5 6 7 1/2/3/4/ 5/6/7.1	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection	a a b	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1 8 1 2 3	Tanks Propellant tanks Pressure tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes	a a b	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc.
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1	Tanks Propellant tanks Pressure tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes Passive coolers	a a b c a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc. Coating and Insulation (surface thermal control)
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1 8 1 2 3 4 5	Tanks Propellant tanks Pressure tanks Pressure tanks Pairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes Passive coolers Thermal Engineering SW	a a b c a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc. Coating and Insulation (surface thermal control) SW for Thermal design, analysis, simulation, etc.
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1 8 1 2 3 4 5 6	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes Passive coolers Thermal Engineering SW Other	a a b c a a a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc. Coating and Insulation (surface thermal control) SW for Thermal design, analysis, simulation, etc. Ventilation piping and venting
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1 8 1 2 3 4 5	Tanks Propellant tanks Pressure tanks Pressure tanks Pairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes Passive coolers Thermal Engineering SW	a b c a a a a a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc. Coating and Insulation (surface thermal control) SW for Thermal design, analysis, simulation, etc. Ventilation piping and venting Heaters
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1 8 1 2 3 4 5 6	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes Passive coolers Thermal Engineering SW Other	a a b c a a a a b b b	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc. Coating and Insulation (surface thermal control) SW for Thermal design, analysis, simulation, etc. Ventilation piping and venting Heaters Temp. Sensors Heat flow control and distribution devices (Pipes,
			Thermal	3 4 5 6 7 1/2/3/4/ 5/6/7.1 8 1 2 3 4 5 6	Tanks Propellant tanks Pressure tanks Fairing Payload adapters Other Structures - BB Structural Engineering SW Thermal Protection Heat storage and rejection Heat pipes Passive coolers Thermal Engineering SW Other	a b c a a a a a	Intestages, skirts, thrust frame, Structural joints, dampers, interfaces support, interface rings, Plates panels and bearing walls Other SW for Structures design, analysis, simulation, etc. Coating and Insulation (surface thermal control) SW for Thermal design, analysis, simulation, etc. Ventilation piping and venting Heaters Temp. Sensors



2.2 Satellites & Probes

Segment Systems Systems Systems Segment Segm						Duaduata		
Segment Systems Components Component								
Securities & A AOCS & GNC 1 Sensors 0 Accelerometers 0 Cartis Sensors 0 C		_		_				
II Satellites & A AOCS & GNC Probes AOCS & GNC I Sensors		Segment		Systems				Description
### ADCS & GNC Probes ADCS & GNC Sensors								
Dearth Sensors		C-t-IIIt 0		AOCC A CNC	4			
Committee Comm	111		Α	AUCS & GNC	1	Sensors		
B		Probes						
B. Inertial Mesurement Units (IMUs)							-	
Tolerand New Average Count (Institution (I								
Option Navigation Units (Including 3D cameras) 1 Star Trackers 1 Sun Sensors 2 Sun Sen								
Sensors - BB Star Trackers Sensors - BB Sensors - BB Sensors - BB Sensors - BB Sensors - BB Sensors - BB Sensors - BB Sensors - BB								
Sensors - BB A Detectors (APS, CCC), Infrared detectors,)								
1.1 Sensors – BB a Detectors (APS, CCD, infrared detectors,) Sensors – BB a Detectors (APS, CCD, infrared detectors,) Electronics (proximity/ analog processing, digital conversion, etc.)								
Belectronics Copylical heads							j	
Coptical heads					1.1	Sensors - BB	а	Detectors (APS, CCD, infrared detectors,)
Coptical heads Coptical heads Coptical heads Coptical heads Control Mement Gyros Control Systems (low-thrust) C							٦	Electronics (proximity/ analog processing, digital conversion,
Actuators							ם	etc.)
Actuators							С	Optical heads
B Cantrol Moment Gyros							d	Other
C Magnetorquers					2	Actuators	а	Wheels (Momentum, Reaction)
Actuators - BB								
Actuators - BB								
Actuators - BB								
Bactuators Mechanisms "See Mechanisms Call Editation Call Hotel					2 1	Astuntous DD		
C Electrical motors "See Mechanisms d Other Control (GNC) 4 AOCS & GNC On Board SW 5 AOCS & GNC Eng. SW 6 AOCS & GNC Eng. SW 8 Electronics 1 EEE Components 6 C II EEE Components 7 Fuses 8 Electronics 1 EEE Components 8 Electronics 1 See On Board Data Management 8 C Connectors 9 C Crystals 9 Magnetic components (e.g. Inductors, Transformers) 1 Surface acoustic wave devices 2 Mores and cables 2 Mores and cables 2 Mores and cables 3 Composite Materials 4 Reinforcement Material: Glass Fibres 5 Reinforcement Material: Silicon Carbide, both Fibre and Particulate (AI-D) 6 Reinforcement Material: Alumina, both Fibre and Particulate (AI-D) 7 Reinforcement Material: New polymeric fibres 9 Reinforcement Material: New polymeric fibres 1 Matrix Structure: Epoxy 1 Matrix Structure: Epoxy 1 Matrix Structure: Caramic (SIC) 1 Matrix Structure: Caramic (SIC)					2.1	Actuators – BB		
Barrials Guidance Navigation Control (GNC) Bythird Navigation Units (IMU/GPS,) Control (GNC)							_	
B Guidance Navigation Control (GNC) Co								
Control (GNC) Display Support Support					3	Guidance Navigation		
4 AOCS & GNC On Board SW 5 AOCS & GNC Eng. SW a SW for AOCS&GNC design, analysis, simulation, etc. B Electronics 1 EEE Components					3			
4 ACCS & GNC On Board SW 5 AOCS & GNC Eng. SW a SW for AOCS&GNC design, analysis, simulation, etc. 5 AOCS & GNC Eng. SW a SW for AOCS&GNC design, analysis, simulation, etc. 6 Connectors C Crystals d Discrete semiconductors (including diodes, transistors) e Filters F uses G Magnetic components (e.g. Inductors, Transformers) h Monolithic Microcircuits (including MMICS) Hybrid dircuits Resistors, heaters 1 Surface acoustic wave devices m Switches (including mechanical, thermal) n Themstors o Wires and cables Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) Passive Microwave Devices (including for instance, mixers, couplers, isolators and switches) C Materials								
SW ACCS & GNC Eng. SW a SW for AOCS&GNC design, analysis, simulation, etc.					4	AOCS & GNC On Board		
B Electronics 1							а	*See On Board Data Management
b Connectors c Crystals d Discrete semiconductors (including diodes, transistors) e Filters f Fuses g Magnetic components (e.g. Inductors, Transformers) h Monolithic Microcircuits (including MMICs) i Hybrid circuits j Relays k Resistors, heaters l Surface acoustic wave devices m Switches (including mechanical, thermal) n Thermistors o Wires and cables p Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) q Passive Microwave Devices (including for instance, mixers, couplers, isolators and switches) r Other C Materials 1 Metallic 2 Non-metallic 3 Composite Materials b Reinforcement Material: Glass Fibres c Reinforcement Material: Aramid Fibres d Reinforcement Material: Aramid Fibres c Reinforcement Material: Silicon Carbide, both Fibre and Particulate (GlC) f Reinforcement Material: New polymeric fibres g Reinforcement Material: New polymeric fibres g Reinforcement Material: New polymeric fibres h Matrix Structure: Epoxy i Matrix Structure: Epoxy i Matrix Structure: Gramic (SiC) k Matrix Structure: Cyanate Ester j Matrix Structure: Cyanate Ester j Matrix Structure: Cyanate Ester					5	AOCS & GNC Eng. SW	а	SW for AOCS&GNC design, analysis, simulation, etc.
C Crystals d Discrete semiconductors (including diodes, transistors) e Filters f Fuses g Magnetic components (e.g. Inductors, Transformers) h Monolithic Microcircuits (including MMICs) i Hybrid circuits j Relays k Resistors, heaters 1 Surface acoustic wave devices m Switches (including mechanical, thermal) n Thermistors o Wires and cables Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) q Packy Microwave Devices (including for instance, mixers, couplers, isolators and switches) r Other C Materials 1 Metallic 2 Non-metallic 3 Composite Materials A Reinforcement Material: Glass Fibres b Reinforcement Material: Carbon Fibres c Reinforcement Material: Silicon Carbide, both Fibre and Particulate (SiC) Reinforcement Material: Alumina, both Fibre and Particulate (SiC) Reinforcement Material: New polymeric fibres g Reinforcement Material: Others h Matrix Structure: Cyanate Ester j Matrix Structure: Cyanate Ester j Matrix Structure: Ceramic (SiC)			В	Electronics	1	EEE Components	а	Capacitors
d Discrete semiconductors (including diodes, transistors) e Filters f Fuses g Magnetic components (e.g. Inductors, Transformers) h Monolithic Microcircuits (including MMICs) i Hybrid circuits j Relays k Resistors, heaters l Surface acoustic wave devices m Switches (including mechanical, thermal) n Thermistors o Wires and cables displays, sensors) q Passive Microwave Devices (including opto-couplers, LED, CCDs, displays, sensors) q Passive Microwave Devices (including for instance, mixers, couplers, isolators and switches) r Other Othe							b	Connectors
E Filters Fisses g Magnetic components (e.g. Inductors, Transformers)							С	Crystals
Fuses g Magnetic components (e.g. Inductors, Transformers)							d	Discrete semiconductors (including diodes, transistors)
g Magnetic components (e.g. Inductors, Transformers) h Monolithic Microcircuits (including MMICs) i Hybrid circuits j Relays k Resistors, heaters l Surface acoustic wave devices m Switches (including mechanical, thermal) n Thermistors o Wires and cables Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) Passive Microwave Devices (including for instance, mixers, couplers, Isolators and switches) r Other C Materials 1 Metallic 2 Non-metallic 3 Composite Materials a Reinforcement Material: Glass Fibres b Reinforcement Material: Carbon Fibres c Reinforcement Material: Aramid Fibres Reinforcement Material: Silicon Carbide, both Fibre and Particulate (SIC) Reinforcement Material: Alumina, both Fibre and Particulate (SIC) Reinforcement Material: New polymeric fibres g Reinforcement Material: Others h Matrix Structure: Epoxy i Matrix Structure: Epoxy i Matrix Structure: Epoxy i Matrix Structure: Cyanate Ester j Matrix Structure: Ceramic (SIC) k Matrix Structure: Metal (Al, Ti, C)								
h Monolithic Microcircuits (including MMICs) i Hybrid circuits j Relays k Resistors, heaters Usurface acoustic wave devices m Switches (including mechanical, thermal) n Thermistors o Wires and cables Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) Passive Microwave Devices (including for instance, mixers, couplers, isolators and switches) r Other C Materials 1 Metallic 2 Non-metallic 3 Composite Materials a Reinforcement Material: Glass Fibres b Reinforcement Material: Carbon Fibres c Reinforcement Material: Alumina, both Fibre and Particulate (SIC) Reinforcement Material: Alumina, both Fibre and Particulate (Al ₂ O ₃) f Reinforcement Material: New polymeric fibres g Reinforcement Material: New polymeric fibres h Matrix Structure: Epoxy i Matrix Structure: Epoxy i Matrix Structure: Ceramic (SIC) Matrix Structure: Ceramic (SIC) Matrix Structure: Ceramic (SIC) Matrix Structure: Metal (Al, Ti, C)							-	
Hybrid circuits j. Relays k. Resistors, heaters l. Surface acoustic wave devices m. Switches (including mechanical, thermal) n. Thermistors Owires and cables Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) Passive Microwave Devices (including for instance, mixers, couplers, isolators and switches) r. Other C Materials 1								
Jacaba Relays							_	
Resistors, heaters Surface acoustic wave devices Surface acoustic wave devices m Switches (including mechanical, thermal)							i	
Surface acoustic wave devices m Switches (including mechanical, thermal)							j	
m Switches (including mechanical, thermal) 1 Thermistors 2 Optoelectronic Devices (including opto-couplers, LED, CCDs, displays, sensors) 4 Passive Microwave Devices (including for instance, mixers, couplers, isolators and switches) 7 Other C Materials 1 Metallic 2 Non-metallic 3 Composite Materials 4 Reinforcement Material: Glass Fibres 5 Reinforcement Material: Carbon Fibres 6 Reinforcement Material: Silicon Carbide, both Fibre and Particulate (SiC) 7 Reinforcement Material: New polymeric fibres 9 Reinforcement Material: Others 1 Metallic 2 Non-metallic 3 Reinforcement Material: Silicon Carbide, both Fibre and Particulate (SiC) 6 Reinforcement Material: New polymeric fibres 9 Reinforcement Material: Others 1 Matrix Structure: Epoxy 1 Matrix Structure: Epoxy 1 Matrix Structure: Ceramic (SiC) 2 Reinforcement (SiC) 3 Reinforcement (SiC) 4 Reinforcement Material: Others 1 Matrix Structure: Ceramic (SiC) 2 Reinforcement (SiC)								
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c Reinforcement Material: Aramid Fibres d Reinforcement Material: Silicon Carbide, both Fibre and Particulate (SiC) e Reinforcement Material: Alumina, both Fibre and Particulate (Al ₂ 0 ₃) f Reinforcement Material: New polymeric fibres g Reinforcement Material: Others h Matrix Structure: Epoxy i Matrix Structure: Cyanate Ester j Matrix Structure: Ceramic (SiC) k Matrix Structure: Metal (Al, Ti, C)								
d Reinforcement Material: Silicon Carbide, both Fibre and Particulate (SiC) e Reinforcement Material: Alumina, both Fibre and Particulate (Al ₂ 0 ₃) f Reinforcement Material: New polymeric fibres g Reinforcement Material: Others h Matrix Structure: Epoxy i Matrix Structure: Cyanate Ester j Matrix Structure: Ceramic (SiC) k Matrix Structure: Metal (Al, Ti, C)							_	
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k Matrix Structure: Metal (Al, Ti, C)							j	·
							k	
							_	Matrix Structure: Others



	Segment		Systems		Products: Equipment/Building Blocks/EEE Components, mechanical Parts and materials		Description
II	Satellites &	D	Mechanisms	1	Mechanisms	а	Deployment (SADM, SADE,)
	Probes						Hold Down and Release
							Instrument specific mechanisms
							Scanning Solar Array Drive Mechanisms (SADMs)
						f	Thrusters orientation (EPPM,)
						g	Other
				1.1	Mechanisms – BB	_	Sensors: Position sensors, Velocity, Acceleration, Stress,
						<u> </u>	Motors: Brushed DC, Brushless DC, Piezo-electric, Stepper, Voice Coil,
						b	
						С	Other
				1.1.1	Mechanisms – C&P		Lubricant (dry, fluid), etc
						b	Motors C&P: Motor housing and shaft, Sliprings,
		L				С	* See Mechanical Parts
		E	On-board SW	1	Operating Systems		
		l		2	Libraries	_	Packet Utilization Standard
		l				b	Command Laws and Algorithms (See specific subsystem)
		l			0 11 /	С	Other
				3	Re-usable / customisable SW applications	а	File management systems,
		F	On-board Data	1	Other On Board Data Management		Control Data Management Units (CDMII) or Catallite Management Units
		ľ	Management	1	On Board Bata Management	а	Central Data Management Units (CDMU) or Satellite Management Units (SMU)
						b	Payload Data Handling Units
							Onboard Storage (Mass Memories, Safeguard Memories)
							Telemetry and Telecommand Units
							Reconfiguration Units
						f	Remote Terminal Units
						g	Other
				1.1	On Board Data Management	а	General Purpose Microprocessors (ERC32, Leon 2)
					- BB	b	General Purpose Digital Signal Processors (e.g ADSP 21020, TMS320xx)
						С	Microcontrollers
						d	Dedicated Signal Processing Processors (e.g. FFT, Compression)
							General Purpose Programable Logic (PLD, FPGA)
		l					Rad Hard Memory
		l				q	High Density Memory Devices (e.g stacked SDRAM, FLASH)
						h	Onboard Communcation (MIL-STD-1553, CAN, SpW, Sensor Bus, Wireless)
		l				i	TM/TC (Formater, encryption)
		l				j	Other
		G	Optical	1	Optical Comm.		Optical terminals
		l	Communication	1.1	Optical Comm – BB	а	Detectors *See AOCS&GNC
		l				_	Electronics (elector-optic modules)
		l				_	Laser sources, modulators
		l					Telescopes
		l					Receivers
		l					Software
		l				g	Tracking, (fine) Pointing and Stabilization mechanisms
		L	Parts	1.1.1	Optical Comm - C&P Mechanical, Optical and	а	* See Mechanical Parts
		ľ	raits	1	Magnetic parts	а	Connecting parts (nuts, bolts, etc), Separating parts (springs, cutters, etc), Spacing Parts, Bearing Parts, Control Parts (gears),
		l				b	Optical Parts (lenses, beam-splitters,)
		l				С	Magnetic Parts
		l				d	Other
1		ᆫ	l			u	0.10.



	Segment		Systems		Products: Equipment/Building Blocks/EEE Components, mechanical Parts and materials		Description
11		Ι	Payloads /	1	RF and microwave	а	Altimeters
	Probes		Instruments		Instruments	b	Imaging Radars
						C	Microwave radiometers
						d	Microwave Telescopes
				2	Traffice Doubling above to a contract	е	Other (Scatterometers,)
				3	InfraRed instruments Optical Instruments	a	Telescopes, Imaging radiometers
				3	optical instruments	b	Imaging spectrometers
						С	Infrared spectroscopy
						d	Lidars
						е	Passive sounders
						f	Optical Telescopes
				4	Other Instruments	а	Gradiometers, Plasma detectors,
				all.1	Instruments - BB		·
		J	Power	1	Generation: Solar	а	Photovoltaic Assemblies
					Photovoltaic	а	Photovoitale Assemblies
				1.1	Generation: Solar Photovoltaic - BB	а	Solar Cells Assemblies (SCA) with inter-connectors and coverglass
						b	Structural/mechanical (rigid honeycomb panels, flexible blankets,)
						С	Solar Cells
						d	Other
				1.1.1	Generation: Solar Photovoltaic – C&P	a	Substrates, cover-glass, coatings, adhesives,
				2	Generation: Solar Thermal	b	Other *See EEE Components
				3			De dicioate de Thermanale atria Consentana (DTCs)
				3	Generation: Nuclear reactors	a b	Radioisotope Thermoelectric Generators (RTGs) Other
				4	Generation: Tethered	D	Other
				5	Storage: Flywheels		
				6	Storage: Fuel cells		
				7	Storage: Batteries		
				8	Power Monitoring and Control	а	PCDUs,
				8.1	Power Monitoring and Control - BB	a b	Batteries Charger/Discharger Regulators (BCR; BDR) Current and voltage sensors and limiters
							Heater Control
						_	Pyro Control
						е	Solar Array Regulator
						f	Other
				8.1.1	Power Monitoring and Control – C&P	а	*See EEE Components
				9	Power Eng. SW	а	SW for Power systems design, analysis, simulation, etc.
		K	Propulsion	1	Chemical Propulsion	а	
						b	Chemical Propulsion Systems
				1.1	Chemical Propulsion – BB	a	Combustion chambers
						b	Nozzles
						C	Tanks *See Structures
						d	Pumps Flow control and distribution devices (pipes, valves, actuators, filters,
						е	pressure transducers, pressure regulators)
				2	Chemical Propulsion	f	Other
				2	Engineering SW	а	SW for Chemical propulsion design, analysis, simulation, etc
				3	Electric Propulsion	а	Electrostatic Propulsion Systems
						b	Electromagnetic Propulsion Systems
1				3.1	Electric Propulsion – BB	С	Electrothermal Propulsion Systems
				3.1	Electric Fropulsion - DD	а	Flow control and distribution devices (Fuel decent valves, pyro-valves, high and low pressure transducers, tubing, brackets,)
						b	Electric modules (Power Processing Unit, Power Supply and Control Unit, Actuator Drive Electron, Radio Frequency Generator, Electrical filter,)
						С	Thruster module (Plasma/Ion Thrusters), Xenon Flow Control Unit, *For Thruster Pointing See Mechanisms
						d	
				4	Floatric Propulsion	е	Other
				4	Electric Propulsion Engineering SW	а	SW for Electric propulsion design, analysis, simulation, etc.
				5	Solar sail		
1	į į	_	<u> </u>	6	Cold gas propulsion		



	Segment		Systems		Products: Equipment/Building Blocks/EEE Components, mechanical Parts and materials		Description
II	Satellites & Probes	L	RF / Microwave Communication (Platform and	1	Antennas	а	Omnidirectional, Helix, Horn, Parabolic, Phased Arrays / Platform vs Payload
			Payloads)	1.1	Antennas - BB	a	Feeds
						b	Antenna Towers and/or Reflectors
						С	Antenna mechanisms (Including control electronics) *See Mechanisms for: Hold down and release/Deployment and trim /Pointing
				_		d	Other
				2	Transmitters	а	X-band, S-Band, Ka band, / Near Earth application, Deep space application, / Platform vs Payload
				3	Receivers	а	X-band, S-Band, Ka band, / Near Earth application, Deep space application, / Platform vs Payload
						b	Navigation Receivers * See AOCS & GNC - Single-frequency (Platform/Low-end missions) - Multiple-frequency (Science mission/hig-end missions)
				4	Repeaters and Transceivers	а	Bent-pipe repeaters, regenarative transponders,
				2/3/4.1	Communication - BB	а	Analog: RF front ends
					(Antennas excluded)	b	Analog: Signal amplifiers
						С	Analog: Power amplifiers (SSPA, TWTA,)
						d	Analog: Clocks (integrated oscillators, time counters,)
						е	Analog: Comparators (Frequency/Phase)
						f	Analog: Microwave generators
						g	Digital: Up/Down Converters
						h	Digital: Cryptographic, Digital Signal Processors
						i	Digital: Encoders/Decoders
						j	Digital: Frequency Synthesisers
						k	Digital: Routers (FDMA,)
							Digital: Filters and Multiplexers
						_	Digital: Switching BB
1						n	Other
1				all.1.1	Communication Systems -	a	*See EEE Components
1				5	RF Comm. Eng. SW	a	SW for RF Comm. design, analysis, simulation, etc.
1		М	System	1	Aerothermodynamic Tools	а	Computational Fluid Dynamics (CFD)
			Engineering		for Design	b	Hypersonic / high enthalpy facilities and plasma facilities
			Software			С	Propulsion stands and rocket / jet interaction facilities
				2	Dependability, Safety and Quality tools		RAMS, FMECA,
				3	Environment Models and	b	Other
				4	Computational Tools System Modelling &	а	Radiation belts, Solar energetic particles, Galactic cosmic rays, Dedicated simulation tools (on-board computer emulators, front-end
				1	Simulation	а	equipment simulation,)
1						b	Mission analysis tools (Orbital modelling and simulation)
						С	Modelling tools (Model development, Non real-time execution, Code generation,)
ĺ						d	Simulator executive tools (run-time environments)
1						е	Other



	Segment		Systems		Products: Equipment/Building Blocks/EEE Components, mechanical Parts and materials		Description
77	Satellites &	N	Structures	1	Satellite Bus		
1	Probes			2	Primary Structures		
				3	Secondary Structures		
				4	Folded structures		
				5	Space structures with	а	Deployable Structures, Adaptive Trusses,
					changing geometries	u	
				6	Optical bench structures	а	Cases, supporting rings,
				/	Inflatable space structures		
				all.1	Structures - BB	-	Central tubes, Bars and rods,
							Plates panels and bearing walls
						-	Pressure tanks (pressure-fed cycle engines)
							Propellant tanks Rings
							Structural joints
						-	Struts, Inserts, Fasteners ,
						h	Other
				8	Struct. Eng. SW		SW for Structure design, analysis, simulation, etc.
		┝	Thormal Country	all.1.1	Structures - C&P	а	* See Parts
		٥	Thermal Control		Thermal Protection for atmospheric entry		Ablative systems products, Reusable systems products
				2	Heat storage and rejection	a	Coating and insulation
						b c	Radiators Thermal Capacitors
						-	Other
				3	Heat Transport	_	
				J	Treat Transport	a	Constance Conductance Heat Pipes (CCHPs) Variable Conductance Heat Pipes (VCHPs)
						-	Heat Pipe Diodes (HPDs) Mini/Micro Heat Pipes
						-	High Temperature Heat Pipes
							Other HPs
						g	High temperature CPL/LHP (Capillary Pumped Loop/Loop Heat Pipe)
						h	Low temperature CPL/LHP (Capillary Pumped Loop/Loop Heat Pipe)
						i	Mini CPL/LHP (Capillary Pumped Loop/Loop Heat Pipe)
						j	Other Capillary Driven Loops
						k	Mechanical Pump Driven Loops (MPDL) - Single and two-phase loops
				4	Cryogenic and Refrigeration	а	Peltiers
						b	Cryostats
						С	Stirling, Pulse Tube, J. Thomson
						d	Reverse turbo Bryton coolers
						е	Microcooling
						f	Sub-kelvin coolers (He-sorption pump coolers, Dilution coolers,)
							Adiabatic de-magnetisation refrigerator, NIS chip cooler,)
							Other
				5	Thermal Engineering SW	а	SW for Thermal design, analysis, simulation, etc.
				all.1	Thermal control - BB	а	Cryostat components, cryogenic tanks, cryogenic rupture discs, liquid Helium valves,
						b	Cold plates
						-	Flow control and transfer components
					Thomas London COD		Heaters, Thermistors, Thermostats,
						е	Pumps
						f	TPL Evaporators, condensers, reservoirs,
				all 4 4			Temp. sensors
1						h	Other
				all.1.1	Thermal control - C&P	а	Coatings (black paints, sulphuric oxidation, aluminium, gold,)
						b	Conductive compounds (graphite-silicon sheets,)
						-	Insulators and refractive materials (MLI,)
		Ļ	Oth - :			d	Other
Щ	l	۲	Other				



2.3 Orbital Transportation & Re-entry Systems

		<u> </u>							
	Segment		Systems		Products: Equipment/Building Blocks		Description		
III	Orbital	Α	Descent &	1	Descent	а	Parachutes		
	Transportation		Recovery	2	Recovery	а	Homing Beacon,		
	& Re-entry	В	GNC	1	Sensors	а	Rendezvous, Gyros, Sun Sensors,		
	Systems			2	GNSS receivers	а	GPS receivers		
				3	Actuators				
		С	Environment	1	ECLS		Pressure, air, water, lighting systems,		
			and Crew Life Support (ECLS)			b	Video/Audio		
						С	Crew Support Items (IVA suit, food storage,)		
						d	Other		
		D	Mechanisms	1	Mechanisms	а	Deployment		
						b	Docking (including visual video target, visual ranging cues,) and Docking separation; Interface Sealing Mechanism (ISM), Hatch door		
						-	Module Separation devices		
							Safety and Destruction Systems SADM and SADE		
						-	Umbelical retraction		
						-	Other		
				1.1	Mechanisms – BB	_			
				1.1	Piechanisms – DD	-	Sensors: Position sensors, Velocity, Acceleration, Stress,		
						b	Motors: Brushed DC, Brushless DC, Piezo-electric, Stepper,		
						С	Other		
		E	On Board Data Mangement	1	On Board Data	а	Central Data Management Units (CDMU)		
					Management	-	On Board Storage (Mass Memories, Safeguard Memories)		
					(HW and SW)	_	Telemetry and Telecommand Units		
						-	Propulsion drive electronics		
						-	Other (Sequential Units,)		
				1.1	On Beaud Date	е			
				1.1	On Board Data Management - BB	а	Processors and controllers (communication processor, data processing,)		
						b	Programmable logics (FPGA, PLD)		
						-	TM/TC (Formatter, encryption)		
							On Board Communcation (MIL-STD-1553, CAN,)		
						-	Other		
		F	Power	1	Generation: Solar Photovoltaic	а	Photovoltaic Assemblies		
				1.1	Generation: Solar Photovoltaic – BB	а	Solar Cells Assemblies (SCA) with inter-connectors and cover- glass		
					Power Storage	b	Structural/mechanical (rigid honeycomb panels, flexible blankets,)		
						-	Solar Cells Other		
				2			Batteries		
				3	Power Storage Power Monitoring and Control		PCDU,		
				2 1		_	Current and voltage concern and !::t		
				3.1	Power Monitoring and Control - BB		Current and voltage sensors and limiters, Other		
		-	Propulsion and Reboost	1	Chemical Propulsion	_	Propellants		
		ľ		_	Chemical Propulsion	_			
				1 1	Chaminal Duanulai	_	Propulsion System Computation shambers		
				1.1	Chemical Propulsion Systems – BB	a b	Combustion chambers Nozzles		
					2,3005	_	Tanks *See Structures		
					Chamical Propulsion		Pumps		
				2		u	·		
						e	Flow control and distribution devices (pipes, valves, actuators, filters, pressure transducers, pressure regulators)		
						Ť	Other		
				2	Chemical Propulsion Engineering SW	а	SW for electric propulsion design, analysis, simulation, etc.		



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	Segment		Systems		Products: Equipment/Building Blocks		Description
III	Orbital	Н	RF	1	Antennas	а	GPS Antenna+H30, S-band Antenna,
	Transportation & Re-entry		Communication	2	TX, RX, Repeaters and Transceivers		
	Systems			2.1	TX, RX, Repeaters and Transceivers - BB	а	Power amplifiers (SSPA,)
						b	Signal Amplifiers
						С	Up/Down Converters,
						d	Other
		Ι	Software	1	Flight SW		
				2	System Engineering SW (for Ground SW see Segment III)	а	Dependability, Safety and Quality tools (RAMS,)
						b	Mission Analysis Tools (Trajectory computation, Propellant masses optimisation, Orbital modelling & simulation,)
						С	System Modelling & Simulation (Aerothermodynamic Tools for Design, Environment,)
						d	Other
		J	Structures Thermal Control	1	Avionics Bay	а	Including rings, shell elements,
				2	Modules structures	а	Cargo, Separation and distancing, Launch Escape System, Reentry Module,
				3	Tanks	-	Pressure Tanks
						b	Propellant Tanks
				4	Other		
				all. 1	Structures - BB	_	Structural joints, dampers, interfaces support,
						_	Adapters
						_	Plates panels and bearing walls Other
					Structure Eng. SW	Ė	
		Ŀ		_	Thermal Protection for	а	SW for Structures design, analysis, simulation, etc.
		K	I nermal Control		atmospheric entry		Ablative Systems products, Reusable Systems products
				2	Heat storage and rejection	_	Coating and insulation (MLI)
						_	Radiators
						С	Other
				3	Heat pipes		
				4	Other		
					Thermal Control - BB	а	Heaters, Thermistors, Thermostats,
				4.1		b	Temp. Sensors
						С	Heat flow control and distribution devices (Pipes, Valves,)
1						d	Other
				5	Thermal Eng.SW	а	SW for Thermal design, analysis, simulation, etc.



2.4 Ground Segment

	Segment		System		Products: Equipment		Description
IV	Ground Segment	Α	Mission Operations	1	Control Centre general equipment	а	Workstations, video signal distribution systems, wall screens,
				2	Mission Control	а	TM/TC, Planning & Scheduling,
						b	Satellite and Ground Segment Simulators (e.g. simsat, eurosim, etc.)
						С	Flight Dynamics Systems and Mission Analysis
						d	Operational Support (POD, GNSS, DDOR,)
						е	Engineering Support (GS S/W dev. and maintenance,)
				3	Operations Execution	а	Configuration management, FOP tools, On-board resource checker,
				4	Other		
		В	Ground Station	1	Antennas	а	Structure & Thermal, Servo / Mechanics, Reflectors, feeds and diplexers, Antenna Control Units (ACUs), Drive Systems,
				2	RF equipment	а	Transmitter and Receiver assemblies, Frequency converters,
				3	Baseband equipment	а	Telemetry and Telecommand equipment, Tracking, Ranging and Doppler measurement equipment, CODECS,
				4	F&T equipment	а	Quartz clocks
						b	Rubidium clocks
						С	Caesium clocks
						d	H-Masers
						e f	Saphire Oscillators Atomic Fountains
						<u> </u>	
						y h	Optical Clocks (cold atoms, laser diodes, optical cavities,)
						-	Test equipment
						Ľ	GPS Receivers
						j	Time Generation and Synchronisation equipment Distribution Amplifiers
						ı	Frequency Combs
						m	
						n	Frequency Dissemination equipment Other
				5	Ground Station	n	Other
				5	Monitoring & Control		
		С	Ground Segment Network (or Ground Comm. sub-net)			а	Interface Equipment (NDIU),
1		D	User Operations			а	Instrument management, Data analysis, PI equipment, etc.
		E	Development and Construction of Space Segment	1	Assembly Integration and Test	а	Electrical Ground Support Equipment (EGSE) and Special Check Out Equipment (SCOE)
			opuce ocyment			b	Mechanical Ground Support Equipment (MGSE) (Containers, stands, handling equipment, mechanical integration tools, protection devices)
						С	Optical Ground Support Equipment
1						d	RF Suitcase
						е	Other
				2	General Support	а	Laboratories equipment (spectrum analysers, power meters,)
						b	Other
		F	Launcher specific Ground Segment				



3 APPENDIX: LIST OF ACRONYMS

A

ACU Antenna Control Unit

ADSP Analog Devices – Digital Signal Processor
 AOCS Attitude and Orbit Control Systems

APS Active Pixel Sensor

B

BB Building Block

BCR Battery Charger RegulatorBDR Battery Discharger Regulator

C

CAN Controller Area Network
 CCD Charge – Coupled Device

CCHP Constance Conductance Heat Pipe
 CDMU Central Data Management Unit
 CFD Computational Fluid Dynamics
 CPL Capillary Pumped Loop
 C&P Components & Parts

D

DC Direct Current

• DDOR Delta Differential On-way Range

\mathbf{E}

• ECLS Environment and Crew Life Support

EEE Electrical, Electronic and Electromechanical
 EGSE Electrical Ground Support Equipment
 EPPM Electric Propulsion Pointing Mechanisms
 ERC32 Embedded Real-time Computer 32-bit

F

• FDMA Frequency Division Multiple Access

• FFT Fast Fourier Transform

• FMECA Failure Mode, Effects and Criticality Analysis

FOP Follow-up Observing Program
 FPGA Field – Programmable Gate Array

• F&T Frequency & Time

G

GNC Guidance, Navigation and Control
 GNSS Global Navigation Satellite System
 GPS Global Positioning System

GPT Generic Product Tree

H

HP Heat PipeHPD Heat Pipe Diode



Ι

IMU Inertial Measurement Unit Interface Sealing Mechanism ISM Intra – Vehicular Activity IVA

L

LED Light - Emitting Diode Loop Heat Pipe LHP

 \mathbf{M}

MGSE Mechanical Ground Support Equipment

Military Standard MIL-STD MLI Multi - Layer Insulation

MMIC Monolithic Microwave Integrated Circuit

MPDL Mechanical Pump Driven Loop

N

NDIU Network Data Interface Unit

NIS Normal metal/Insulator/Superconductor

P

PCDU Power Conditioning and Distribution Unit

Portable Interface PΙ

PLD Programmable Logic Device PRE Pressure Regulation Electronics

R

RAMS Reliability, Availability, Maintainability and Safety

RF Radio Frequency

RTG Radioisotope Thermoelectric Generator

S

SADE Solar Array Drive Electronics SADM Solar Array Drive Mechanisms

Solar Cells Assembly SCA

Special Check Out Equipment **SCOE**

SDRAM Synchronous Dynamic Random Access Memory

Satellite Management Unit SMU

Space Wire SpW

SSPA Solid State Power Amplifier

SW Software

T

TM/TC Telemetry/Telecommand

Technical Note TNTPL Two - Phase Loop

Telemetry, Tracking & Command Thrust – Vector Control TT&C

TVC

TWTA Travelling Wave Tube Amplifier

TX/RX Transmitter/Receiver

VCHP Variable Conductance Heat Pipe